

# FGA20S120M

## 1200V, 20A ShortedAnode™ IGBT

### Features

- High speed switching
- Low saturation voltage:  $V_{CE(sat)} = 1.55V @ I_C = 20A$
- High input impedance
- RoHS compliant

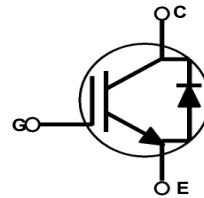
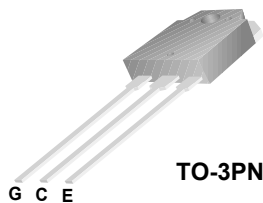
### Applications

- Induction Heating and Microwave Oven
- Soft switching Application



### General Description

Using advanced Field Stop Trench and ShortedAnode technology, Fairchild's 1200V ShortedAnode™ Trench IGBTs offer superior conduction and switching performances, and easy parallel operation with exceptional avalanche capability. This device is designed for Induction Heating and Microwave Oven.



### Absolute Maximum Ratings $T_C = 25^\circ C$ unless otherwise noted

Symbol	Description	Ratings	Units
$V_{CES}$	Collector to Emitter Voltage	1200	V
$V_{GES}$	Gate to Emitter Voltage	$\pm 25$	V
$I_C$	Collector Current @ $T_C = 25^\circ C$	40	A
	Collector Current @ $T_C = 100^\circ C$	20	A
$I_{CM(1)}$	Pulsed Collector Current	60	A
$I_F$	Diode Continuous Forward Current @ $T_C = 25^\circ C$	40	A
$I_F$	Diode Continuous Forward Current @ $T_C = 100^\circ C$	20	A
$P_D$	Maximum Power Dissipation @ $T_C = 25^\circ C$	348	W
	Maximum Power Dissipation @ $T_C = 100^\circ C$	174	W
$T_J$	Operating Junction Temperature	-55 to +175	$^\circ C$
$T_{stg}$	Storage Temperature Range	-55 to +175	$^\circ C$
$T_L$	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds	300	$^\circ C$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction to Case	--	0.43	$^\circ C/W$
$R_{\theta JC}(Diode)$	Thermal Resistance, Junction to Case	--	0.43	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	--	40	$^\circ C/W$

Notes:  
1: Limited by  $T_{jmax}$

### Package Marking and Ordering Information

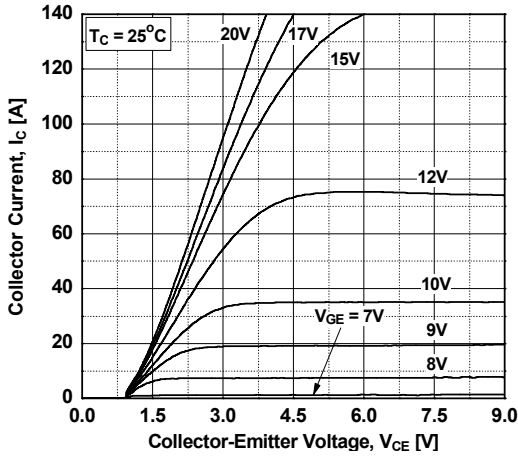
Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FGA20S120M	FGA20S120M	TO-3PN	-	-	30

### Electrical Characteristics of the IGBT T<sub>C</sub> = 25°C unless otherwise noted

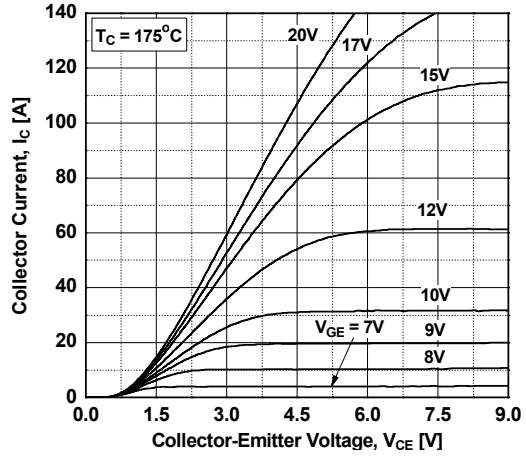
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
<b>Off Characteristics</b>						
BV <sub>CES</sub>	Collector to Emitter Breakdown Voltage	V <sub>GE</sub> = 0V, I <sub>C</sub> = 2mA	1200	-	-	V
I <sub>CES</sub>	Collector Cut-Off Current	V <sub>CE</sub> = V <sub>CES</sub> , V <sub>GE</sub> = 0V	-	-	1	mA
I <sub>GES</sub>	G-E Leakage Current	V <sub>GE</sub> = V <sub>GES</sub> , V <sub>CE</sub> = 0V	-	-	±250	nA
<b>On Characteristics</b>						
V <sub>GE(th)</sub>	G-E Threshold Voltage	I <sub>C</sub> = 20mA, V <sub>CE</sub> = V <sub>GE</sub>	4.5	6.0	7.5	V
V <sub>CE(sat)</sub>	Collector to Emitter Saturation Voltage	I <sub>C</sub> = 20A, V <sub>GE</sub> = 15V T <sub>C</sub> = 25°C	-	1.55	1.85	V
		I <sub>C</sub> = 20A, V <sub>GE</sub> = 15V, T <sub>C</sub> = 125°C	-	1.75	-	V
		I <sub>C</sub> = 20A, V <sub>GE</sub> = 15V, T <sub>C</sub> = 175°C	-	1.85	-	V
V <sub>FM</sub>	Diode Forward Voltage	I <sub>F</sub> = 20A, T <sub>C</sub> = 25°C	--	1.7	2.2	V
		I <sub>F</sub> = 20A, T <sub>C</sub> = 175°C	--	2.1	-	V
<b>Dynamic Characteristics</b>						
C <sub>ies</sub>	Input Capacitance	V <sub>CE</sub> = 30V, V <sub>GE</sub> = 0V, f = 1MHz	--	2680	--	pF
C <sub>oes</sub>	Output Capacitance		--	53	--	pF
C <sub>res</sub>	Reverse Transfer Capacitance		--	43	--	pF
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>CC</sub> = 600V, I <sub>C</sub> = 20A, R <sub>G</sub> = 10Ω, V <sub>GE</sub> = 15V, Resistive Load, T <sub>C</sub> = 25°C	-	43	-	ns
t <sub>r</sub>	Rise Time		-	176	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		-	310	-	ns
t <sub>f</sub>	Fall Time		-	320	480	ns
E <sub>on</sub>	Turn-On Switching Loss		-	0.52	-	mJ
E <sub>off</sub>	Turn-Off Switching Loss		-	1.43	2.15	mJ
E <sub>ts</sub>	Total Switching Loss	-	1.95	-	mJ	
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>CC</sub> = 600V, I <sub>C</sub> = 20A, R <sub>G</sub> = 10Ω, V <sub>GE</sub> = 15V, Resistive Load, T <sub>C</sub> = 175°C	-	41	-	ns
t <sub>r</sub>	Rise Time		-	260	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		-	345	-	ns
t <sub>f</sub>	Fall Time		-	520	-	ns
E <sub>on</sub>	Turn-On Switching Loss		-	0.78	-	mJ
E <sub>off</sub>	Turn-Off Switching Loss		-	1.97	-	mJ
E <sub>ts</sub>	Total Switching Loss	-	2.75	-	mJ	
Q <sub>g</sub>	Total Gate Charge	V <sub>CE</sub> = 600V, I <sub>C</sub> = 20A, V <sub>GE</sub> = 15V	-	208	-	nC
Q <sub>ge</sub>	Gate to Emitter Charge		-	18	-	nC
Q <sub>gc</sub>	Gate to Collector Charge		-	119	-	nC

## Typical Performance Characteristics

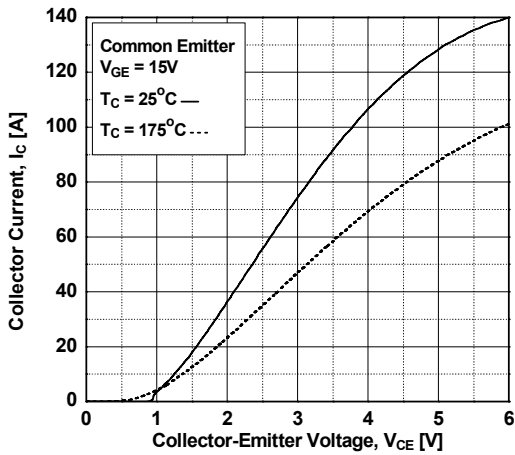
**Figure 1. Typical Output Characteristics**



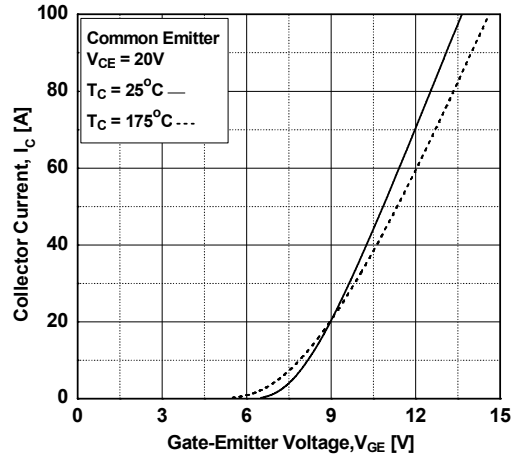
**Figure 2. Typical Output Characteristics**



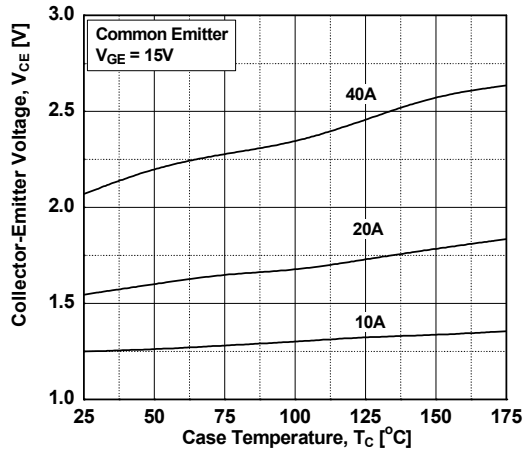
**Figure 3. Typical Saturation Voltage Characteristics**



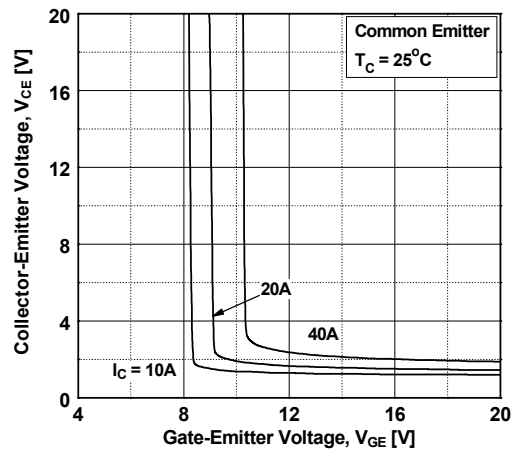
**Figure 4. Transfer Characteristics**



**Figure 5. Saturation Voltage vs. Case Temperature at Variant Current Level**



**Figure 6. Saturation Voltage vs. Vge**



## Typical Performance Characteristics

Figure 7. Saturation Voltage vs.  $V_{GE}$

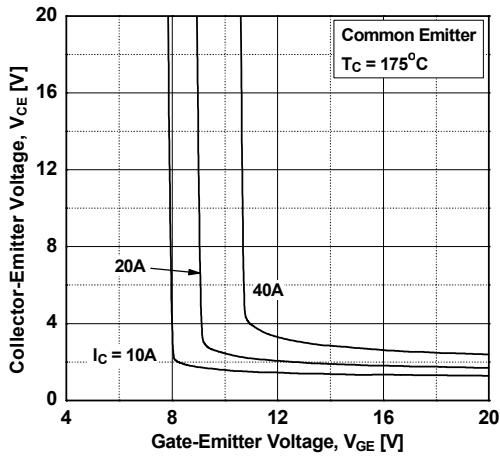


Figure 8. Capacitance Characteristics

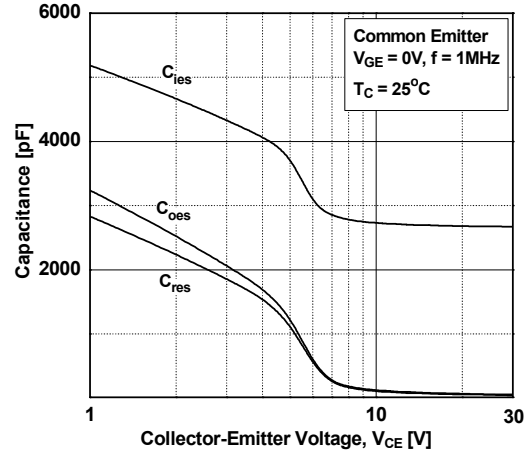


Figure 9. Gate Charge Characteristics

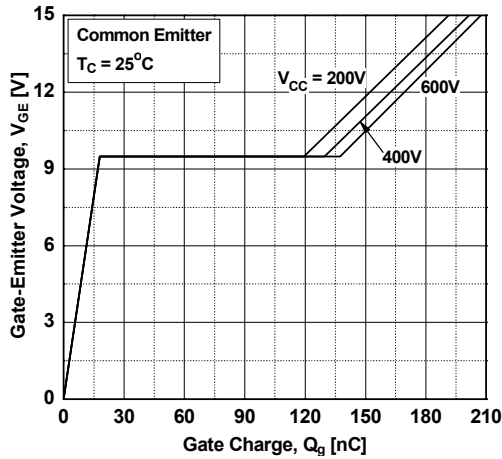


Figure 10. SOA Characteristics

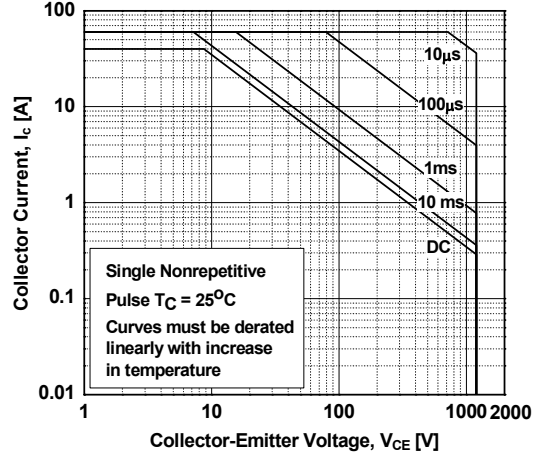


Figure 11. Turn-On Characteristics vs. Gate Resistance

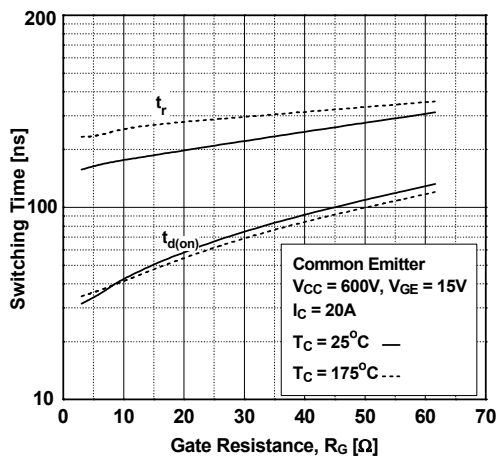
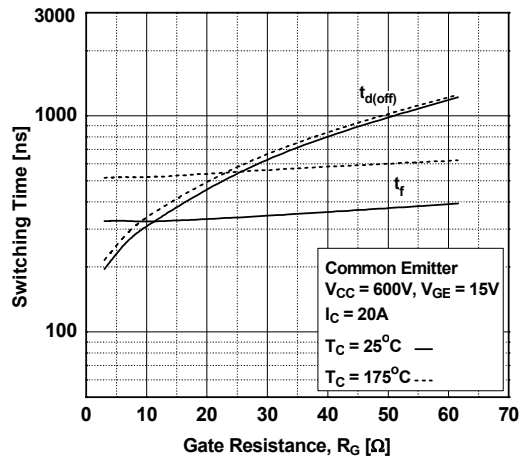
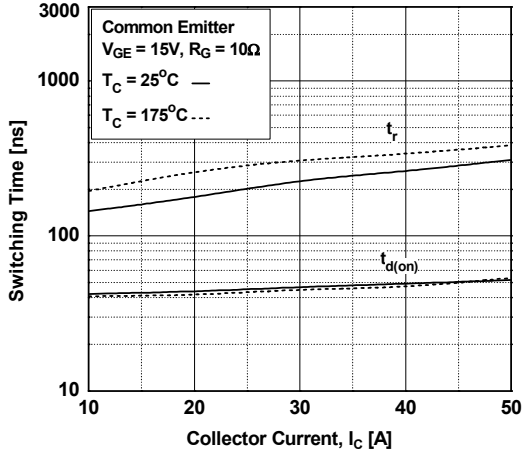


Figure 12. Turn-Off Characteristics vs. Gate Resistance

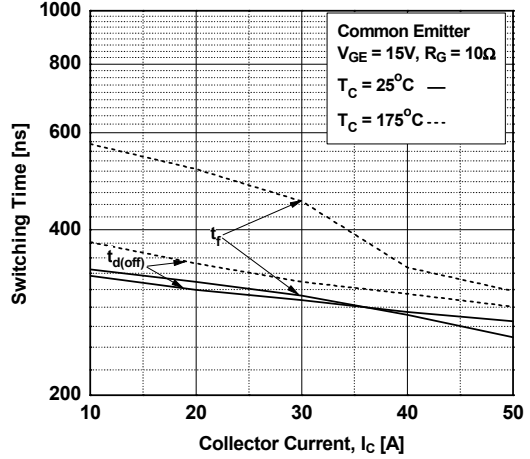


## Typical Performance Characteristics

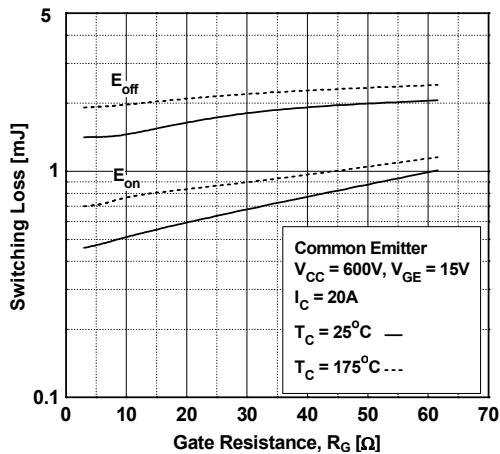
**Figure 13. Turn-On Characteristics vs. Collector Current**



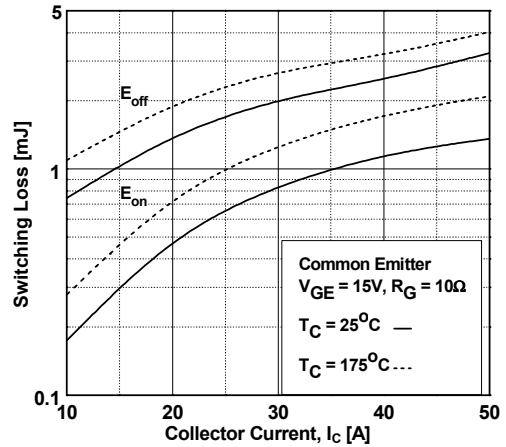
**Figure 14. Turn-off Characteristics vs. Collector Current**



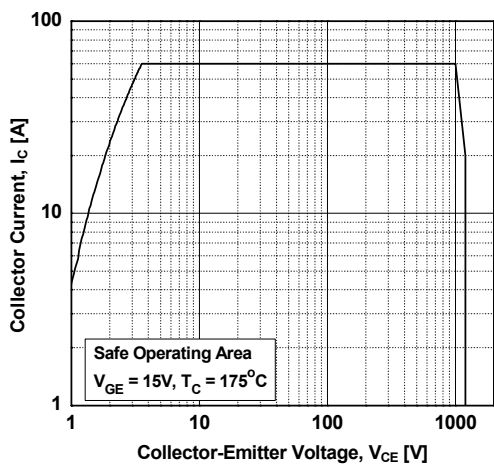
**Figure 15. Switching Loss vs. Gate resistance**



**Figure 16. Switching Loss vs. Collector Current**



**Figure 17. Turn-Off Switching SOA Characteristics Collector Current**



**Figure 18. Diode Forward Characteristics**

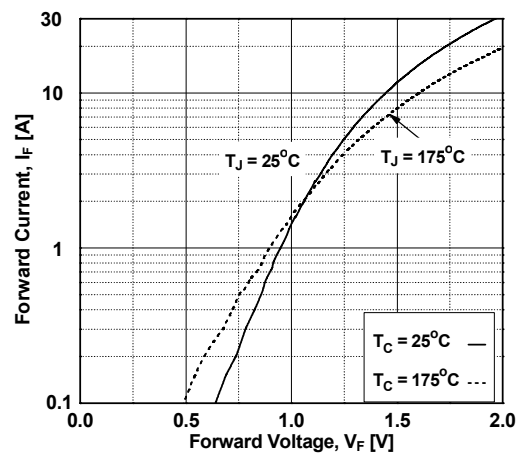
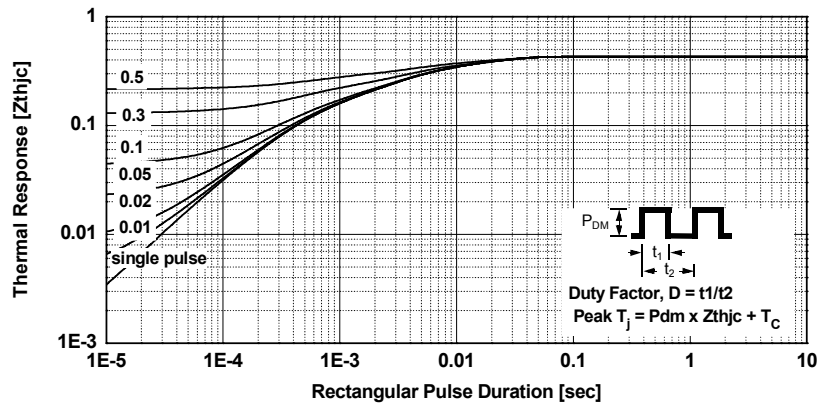
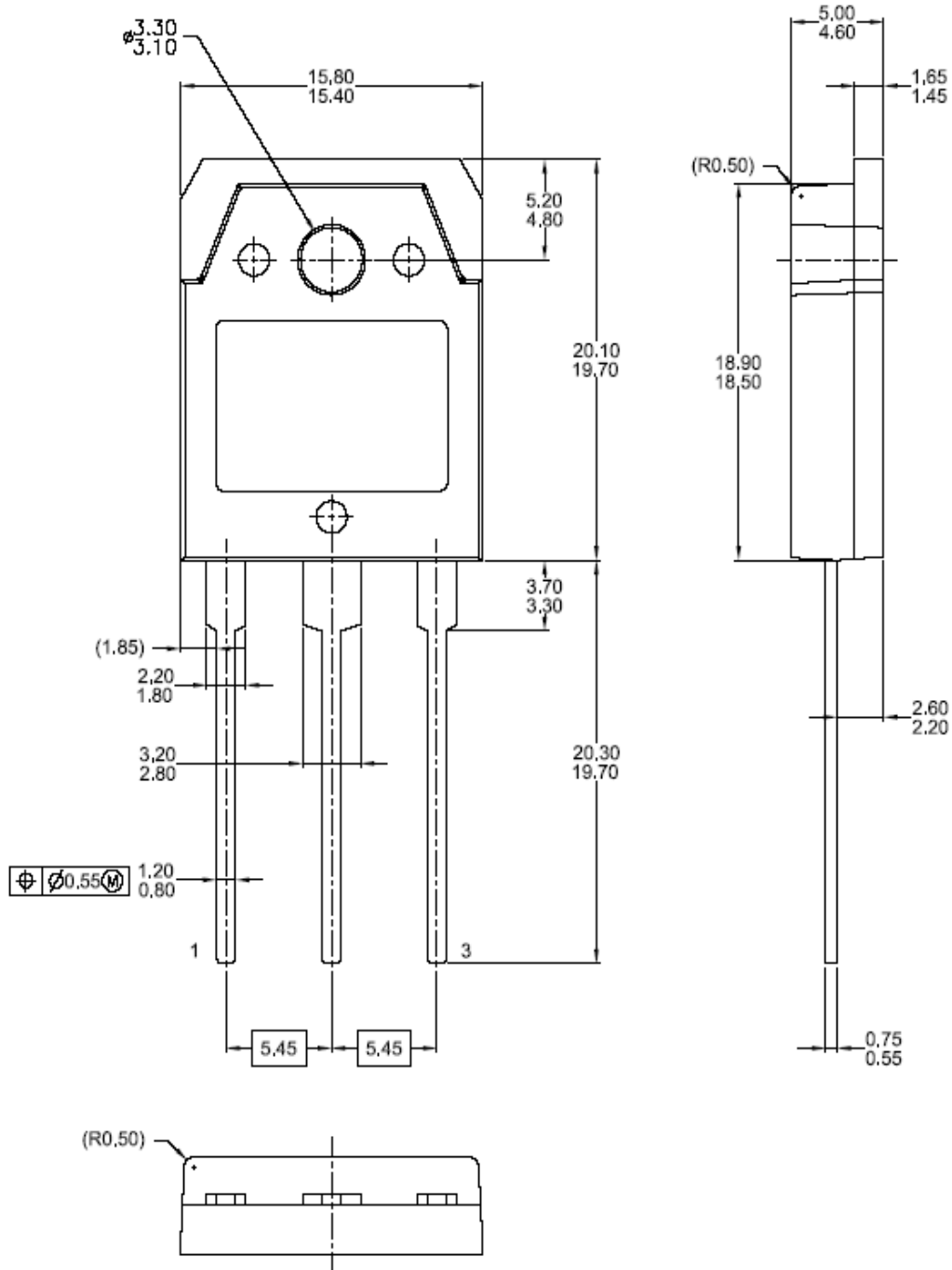


Figure 19. Transient Thermal Impedance of IGBT



Mechanical Dimensions

TO-3PN



Dimensions in Millimeters



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